

# Reverse biased porous silicon light-emitting diodes for optical intra-chip interconnects

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### Abstract

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7 We have reported recent progress in development of the integrated optoelectronic unit on a Si chip. The developed optoelectronic unit includes a porous Si light-emitting diode (LED) connected with a photodetector by an alumina waveguide.

9 Main attention has been devoted to the enhancement of LED parameters. Quantum efficiency as high as 0.4% has been reached. The delay time of 1.2 ns and the rise time of 1.5 ns have been measured for the diodes. Further improvements are also discussed.

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13 PACS: 78.55.Mb; 78.60.Fi; 78.66.-w

Keywords: Light-emitting diode; Photodetector; Porous silicon; Alumina waveguide

## 1. Introduction

Recent developments in communication systems and computer technology make increasingly attractive the substitution of electrons with photons in

19 transmission and processing of information. Thus, optoelectronic interconnects are required for the next

21 generation of integrated systems. Since the discover of an efficient light emission from porous silicon, this

material is considered to be promising for integrated silicon-based optoelectronic systems able to emit,
 transmit, and detect light in the visible range.

We reported on an aluminum/porous silicon junction, which operates like a light-emitting diode (LED) when biased above the avalanche breakdown [1], and

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on an integrated optoelectronic unit including the 29 porous silicon LED connected with a photodetector (PD) by an alumina waveguide [2,3]. The developed 31 avalanche LED can be integrated with conventional CMOS silicon devices in the same chip. In this 33 paper, we present recent extended data characterizing operation of the integrated optoelectronic unit with 35 the avalanche porous silicon LED.

#### 2. Experimental

The main technological steps of fabrication of the integrated optoelectronic unit are described in Ref. 39 [3]. An equivalent scheme of the developed silicon integrated optoelectronic unit is shown in Fig. 1 41 helps understanding the device performance. The unit includes two aluminum/porous silicon Schottky junctions, an alumina layer between them arranged like it is schematically shown in Fig. 1. One of the 45

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1386-9477/02/\$-see front matter © 2002 Published by Elsevier Science B.V. PII: S1386-9477(02)00655-0

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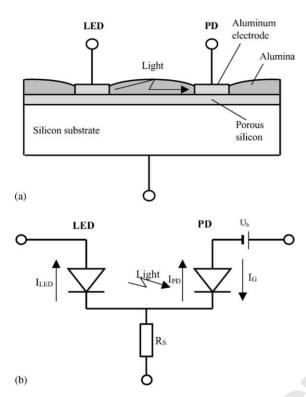


Fig. 1. Schematic diagram of integrated porous silicon optoelectronic unit (a) and its equivalent electric scheme (b).

1 junctions operates as a LED, another as a PD. The distance between them is 7 μm. The anodic aluminum

3 oxide (alumina) protects the porous silicon surface from atmospheric oxygen. Moreover, it plays another
5 important role in the device. The light emitted by

one of the Schottky junctions is transmitted within
the alumina layer as in an optical waveguide. As far as the refractive index of porous silicon (1.3–1.6) is

9 lower than that of alumina (1.65-1.77) [2], the anodic alumina layer provides an appropriate light guiding
11 effect.

The fabricated devices were characterized with time response, transient electroluminescence and delay time techniques. The time response of the avalanche

15 LEDs was measured when the device was biased with a short pulse generator (E1-14). The emitted light

17 passing through a monochromator was detected by a fast photomultiplier. The current through the device

19 was in the range of 10–240 mA. The transient electroluminescence was recorded between the leading and trailing edges of the current pulse measured at 10%21and 90% of the current amplitude corresponding to231.0 ns, which are dominated by RC time constant of23the pulse generator. The delay time was measured by25comparison of the recorded transient characteristics25with a transient characteristic of the reference tunnel27GaAs LED, which had the delay time less than 0.1ns.27

#### 3. Results and discussion

Light is generated when the left Schottky junction is29biased by a voltage close to the avalanche breakdown31and reverse current  $(I_{LED})$  passes through it. Meantime31reverse current appears in the right Schottky junction33tion is experimentally recorded to increase with an35behavior is observed for an external light irradiation of35this junction. So, we conclude that the measured current is a photo response of the right Schottky junction.37

There is a galvanic link between the LED and the 39 PD (see Fig. 1). However, the direction of the galvanic current  $(I_G)$  is opposite to the measured PD current 41  $(I_{\rm PD})$ . In order to reduce the influence of the galvanic current, we have used an additional batteries of 1.5-43 3 V connected with the PD, as it is shown in the Fig. 1. Moreover, the substrate resistance  $(R_S)$  is about 10  $\Omega$ , 45 and simple calculation shows, that for  $I_{\text{LED}}$  less than 100 mA the  $I_{\rm G}$  could not change the PD bias. But for 47 the  $I_{\text{LED}}$  above this value the  $I_{\text{G}}$  affects the PD bias, 49 thus resulting in the decrease of the  $I_{PD}$  values. The increase of  $I_{\rm LED}$  can even change the polarity of  $I_{\rm PD}$ due to inversion of the net PD voltage. It is obvious 51 that this effect takes place for various battery biases at different  $I_{\text{LED}}$  values, as shown in Fig. 2. 53

The relationship between  $I_{PD}$  and  $I_{LED}$  is close to quadratic dependence. Meantime, the relationship 55 between LED electroluminescence and  $I_{LED}$  is also quadratic [5]. It confirms that the PD response originates from LED light emission. 57

The ratio of  $I_{PD}$  to  $I_{LED}$  reaches 0.4%. This value 59 can be considered as a quantum efficiency of the LED. The external quantum efficiency measured by an external PD was one order less. It means, that the light from the integrated LED mostly propagates through 63 the alumina waveguide in the horizontal direction. It should be noted that the developed optoelectronic unit 65

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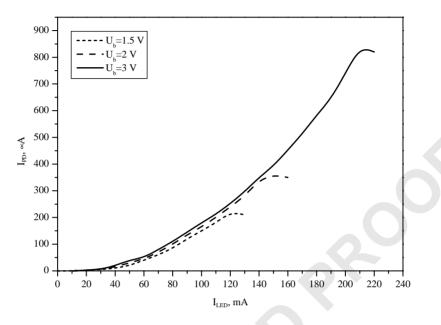


Fig. 2. PD current versus LED current in the porous silicon-based optoelectronic unit with 7 µm alumina waveguide between LED and PD.

1 still has perspectives to be further optimized in order to reduce optical losses in the waveguide and to in-

3 crease the PD efficiency. This work is in progress. Special attention has been paid to the time re-

- sponse of the LED. The transient electroluminescence wave form with the minimized time response is
  shown in Fig. 3. This curve corresponds to the lowest
- series resistance and capacitance in the LED. The basic9 feature of the transient electroluminescence can be

characterized by the delay time (time delay between the moment when the drive pulse is applied and the moment when light response becomes visible) and the

rise time. The delay time of 1.2 ns and the rise time of 1.5 ns can be extracted from the curve presented

15 in Fig. 3 for the voltage pulse of 12 V.

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The shortest time response is observed for the maximum bias applied, as it was also described in Ref. [6]

- for forward biased porous silicon LEDs. However, our electroluminescence devices are faster in comparison
- with the forward biased porous silicon LEDs, because
- 21 in our case there is no an injection capacitance, which limits the time response of the light emission. Dur-

23 ing the light emission from reverse biased junctions the main mechanism of the minor carrier generation

25 is impact ionization at avalanche breakdown. High

electric fields are necessary for that. The regular27columnar structure of porous silicon promotes the27avalanche breakdown due to nonuniform electric field29distribution inside the porous layer [7]. The effect29of impact ionization at avalanche breakdown is very31is estimated to be about 10 ps [8]. The faster carrier33generation mechanism explains the shorter time re-33sponse of our devices in comparison with forward35

Thus, we have shown that the developed LED can operate in the nanosecond range. It should be noted 37 that it is not a limit for these devices. By further technology optimization we hope to reach the subnanosecond range, that is promising for LED applications in optical intra-chip interconnects. 41

## 4. Conclusion

The analysis of reverse biased PS LED developments for the last 10 years has shown the considerable parameter improvement towards practical implementations of these devices in optoelectronics. The only unresolved problem is insufficient LED efficiency. 47

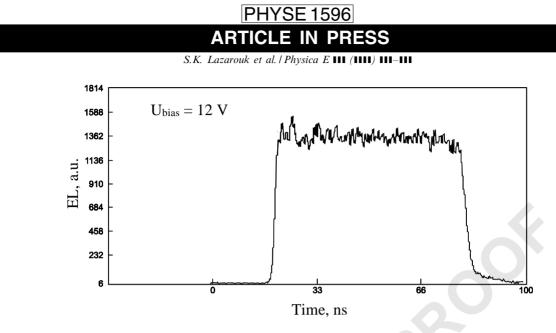


Fig. 3. Electroluminescence time response of the porous silicon LED operating in the avalanche breakdown regime.

- 1 Nevertheless, the achieved efficiency level of about 1% allows us to consider some special applications.
- 3 In particular, reverse biased LEDs could be used for optical intra-chip interconnects. The fabricated pro-
- 5 totype of optoelectronic unit based on these LEDs has demonstrated the possibility of using photons for
- 7 communications inside silicon chips.

#### 5. Uncited reference

9 [4]

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